Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - soldering point (Pin 4)	R_{thJS}	-	-	25	K/W
SMD version, device on PCB:	R_{thJA}				
@ min. footprint		-	-	115	
@ 6 cm^2 cooling area [1)]		-	-	70	

Electrical Characteristics, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain-source breakdown voltage V_{GS}=0, I_D=250µA	$V_{(BR)DSS}$	240	-	-	V
Gate threshold voltage, V_{GS} = V_{DS} I_D=108µA	$V_{GS(th)}$	0.6	1	1.4	
Zero gate voltage drain current	I_{DSS}				µA
V_{DS}=240V, V_{GS}=0, T_j=25°C		-	-	0.1	
V_{DS}=240V, V_{GS}=0, T_j=150°C		-	-	10	
Gate-source leakage current V_{GS}=20V, V_{DS}=0	I_{GSS}	-	1	10	nA
Drain-source on-state resistance V_{GS}=2.8V, I_D=0.014A	$R_{DS(on)}$	-	4.9	15	Ω
Drain-source on-state resistance V_{GS}=4.5V, I_D=0.32A	$R_{DS(on)}$	-	4.6	7.5	
Drain-source on-state resistance V_{GS}=10V, I_D=0.35A	$R_{DS(on)}$	-	4	6	

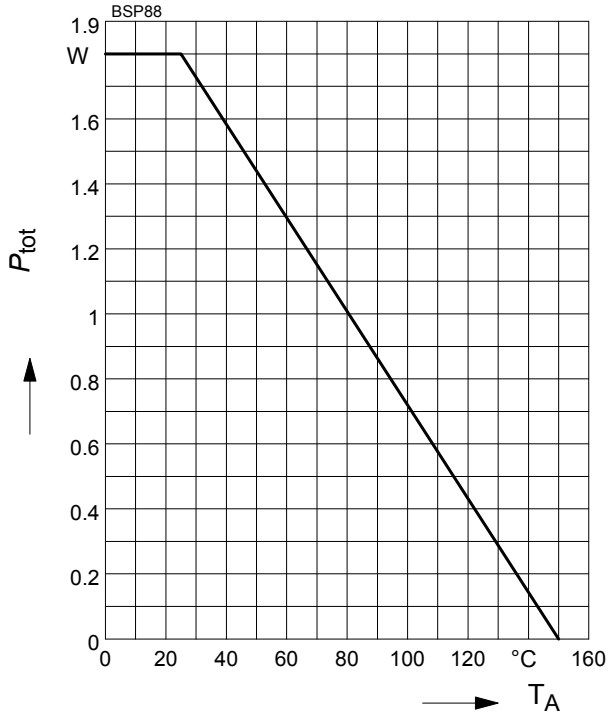
[1]Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical without blown air.

Electrical Characteristics, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic Characteristics						
Transconductance	g_{fs}	$V_{DS}\geq 2*I_D*R_{DS(on)max}$, I_D=0.28A	0.19	0.38	-	S
Input capacitance	C_{iss}	V_{GS}=0, V_{DS}=25V, f=1MHz	-	76	95	pF
Output capacitance	C_{oss}		-	12	15	
Reverse transfer capacitance	C_{rss}		-	6	9	
Turn-on delay time	$t_{d(on)}$	V_{DD}=120V, V_{GS}=4.5V, I_D=0.35A, R_G=15Ω	-	3.6	5.4	ns
Rise time	t_r		-	3.5	5.2	
Turn-off delay time	$t_{d(off)}$		-	17.9	26.8	
Fall time	t_f		-	18.9	28.3	
Gate Charge Characteristics						
Gate to source charge	Q_{gs}	V_{DD}=192V, I_D=0.35A	-	0.2	0.3	nC
Gate to drain charge	Q_{gd}		-	2	3	
Gate charge total	Q_g	V_{DD}=192V, I_D=0.35A, V_{GS}=0 to 10V	-	4.5	6.8	
Gate plateau voltage	$V_{(plateau)}$	V_{DD}=192V, I_D = 0.35 A	-	2.7	-	V
Reverse Diode						
Inverse diode continuous forward current	I_S	T_A=25°C	-	-	0.35	A
Inv. diode direct current, pulsed	I_{SM}		-	-	1.4	
Inverse diode forward voltage	V_{SD}	V_{GS}=0, I_F = I_S	-	0.86	1.2	V
Reverse recovery time	t_{rr}	V_R=120V, I_F=I_S, di_F/dt=100A/µs	-	66	82	ns
Reverse recovery charge	Q_{rr}		-	119	149	nC

1 Power dissipation

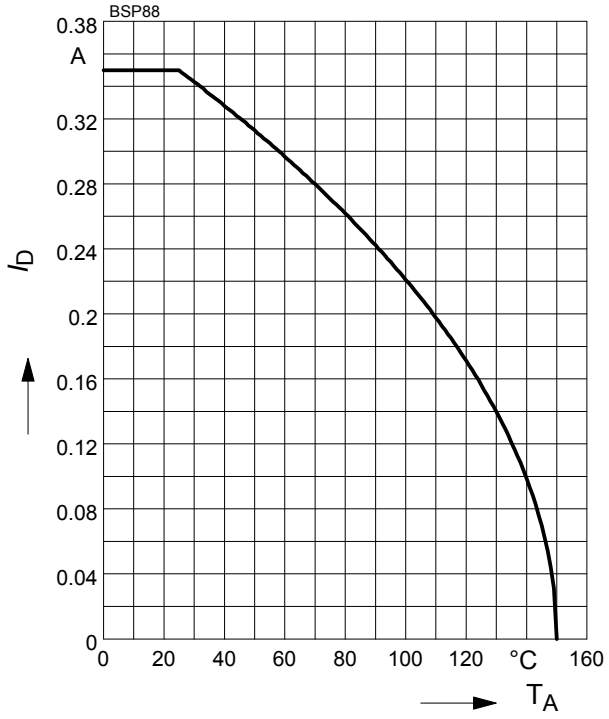
$P_{tot} = f(T_A)$



2 Drain current

$I_D = f(T_A)$

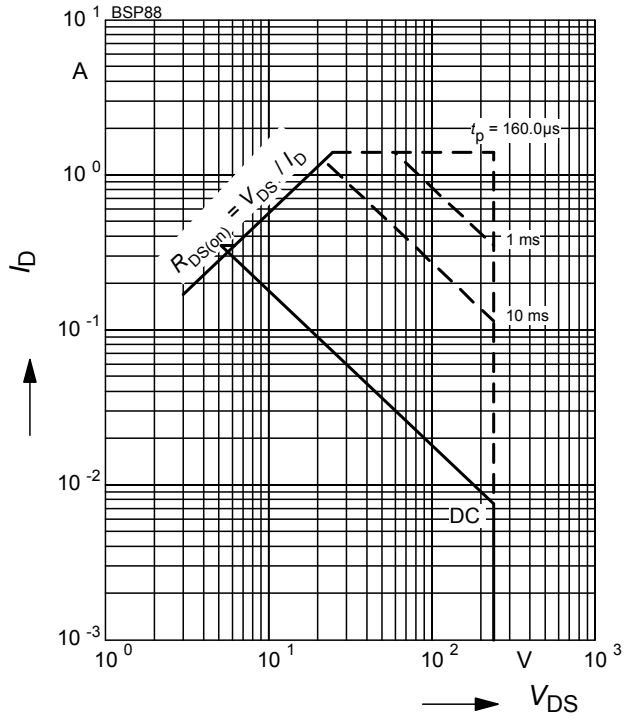
parameter: $V_{GS} \geq 10$ V



3 Safe operating area

$I_D = f(V_{DS})$

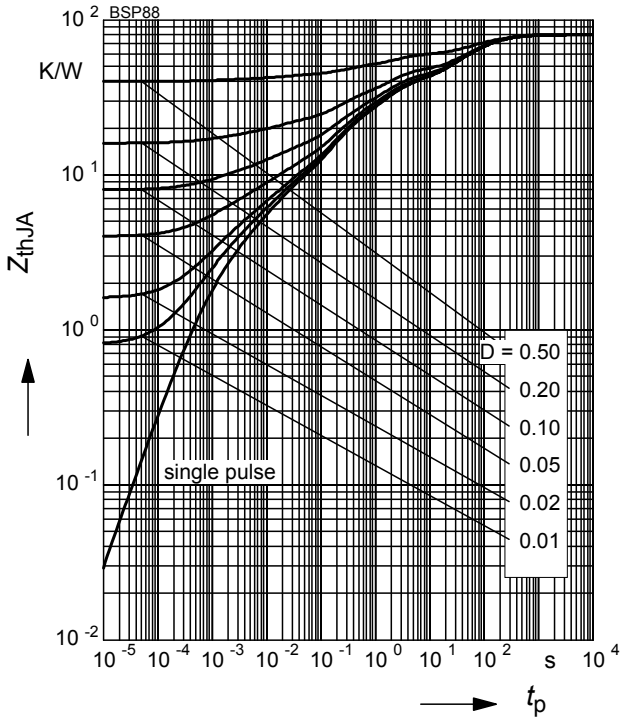
parameter : $D = 0$, $T_A = 25$ °C



4 Transient thermal impedance

$Z_{thJA} = f(t_p)$

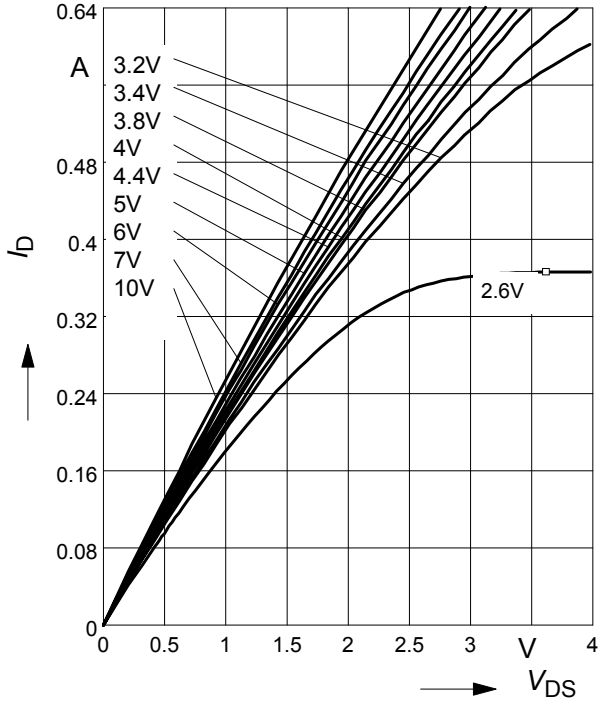
parameter : $D = t_p/T$



5 Typ. output characteristic

$I_D = f(V_{DS})$

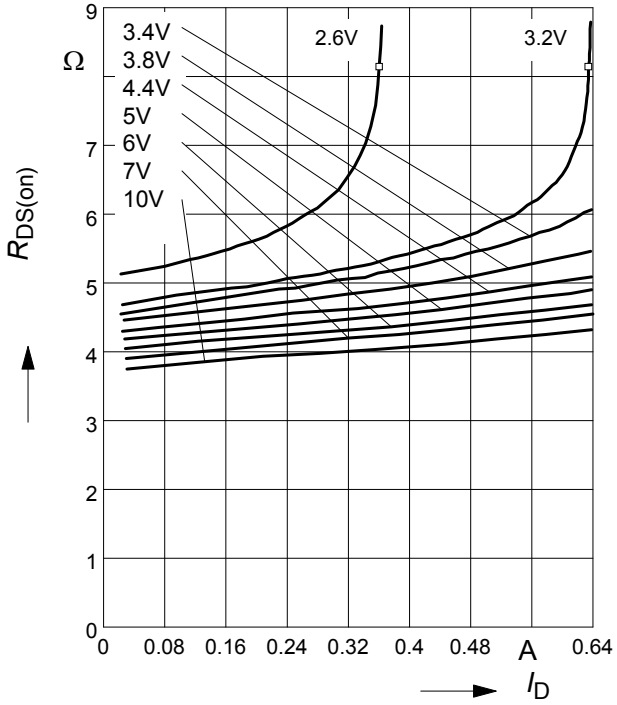
parameter: T_j = 25 °C, V_{GS}



6 Typ. drain-source on resistance

$R_{DS(on)} = f(I_D)$

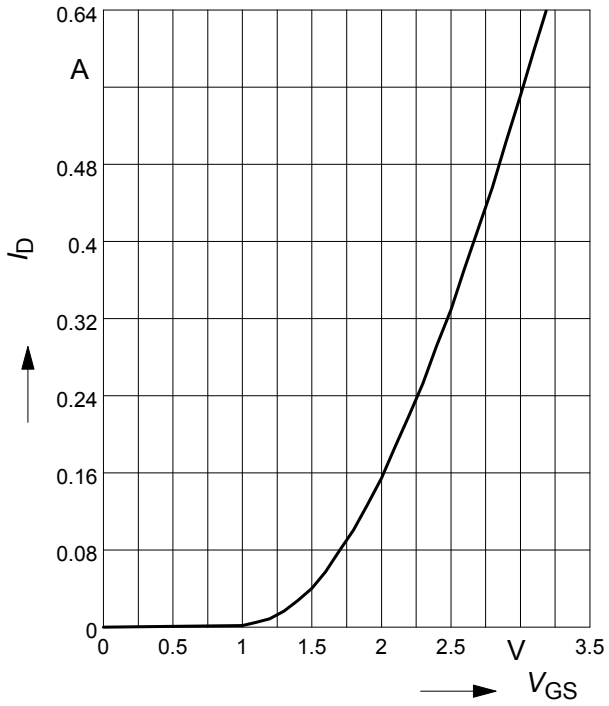
parameter: T_j = 25 °C, V_{GS}



7 Typ. transfer characteristics

$I_D = f(V_{GS})$; $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$

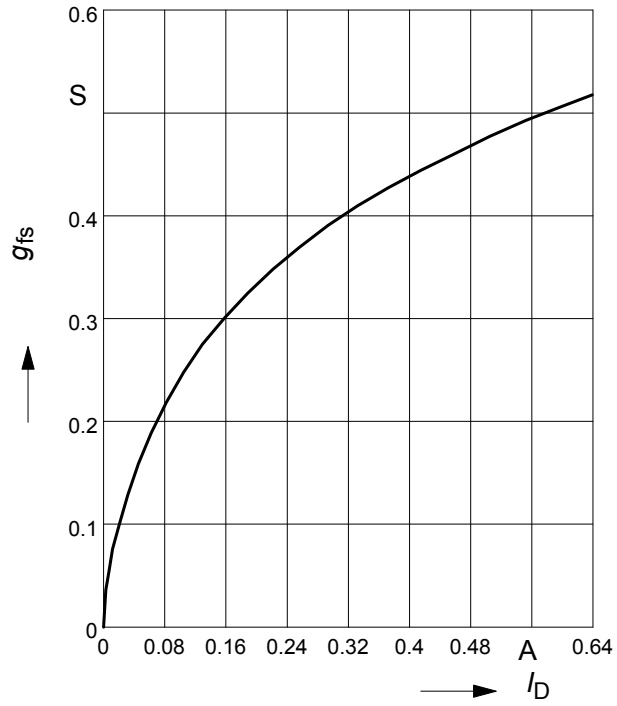
parameter: T_j = 25 °C



8 Typ. forward transconductance

$g_{fs} = f(I_D)$

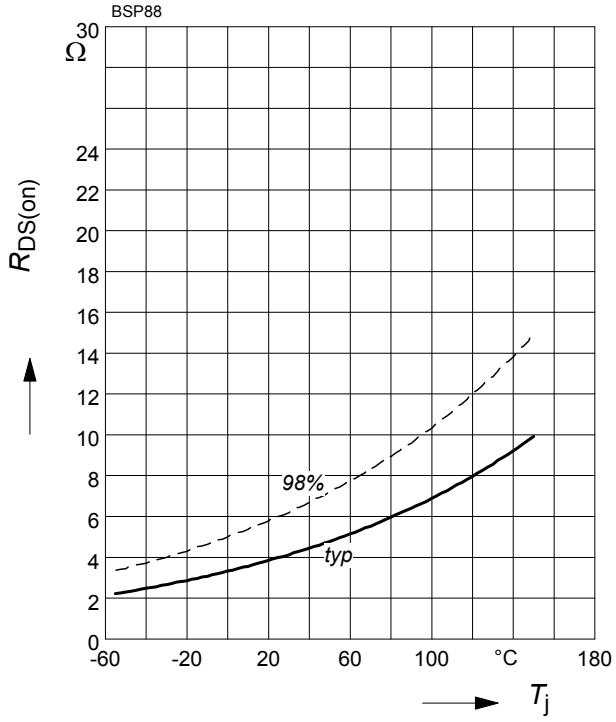
parameter: T_j = 25 °C



9 Drain-source on-state resistance

$R_{DS(on)} = f(T_j)$

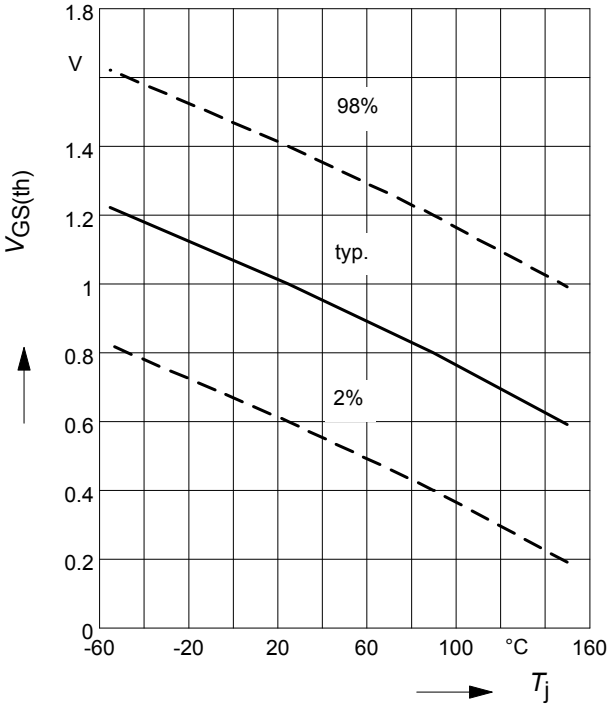
parameter : I_D = 0.35 A, V_{GS} = 10 V



10 Typ. gate threshold voltage

$V_{GS(th)} = f(T_j)$

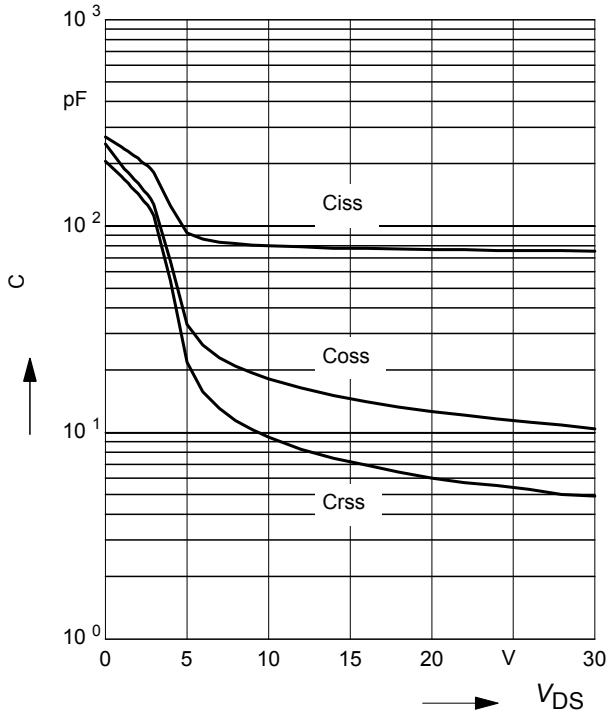
parameter: $V_{GS} = V_{DS}$; I_D = 108 µA



11 Typ. capacitances

$C = f(V_{DS})$

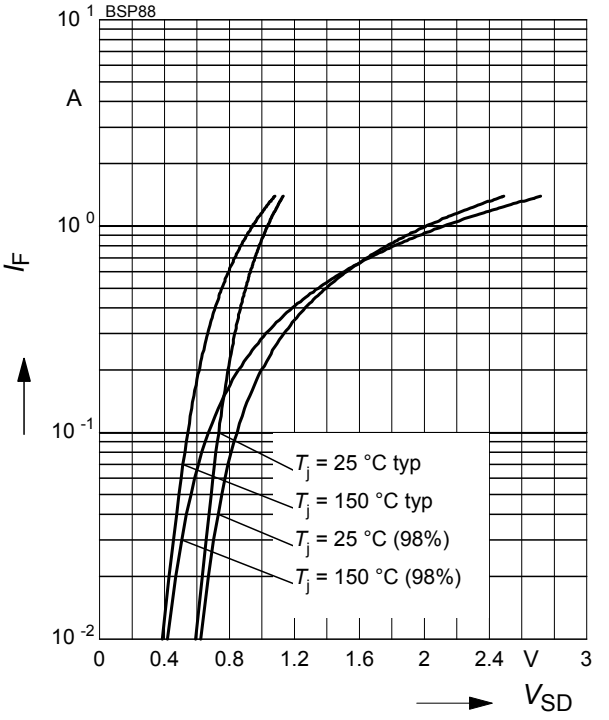
parameter: V_{GS}=0, f=1 MHz, T_j = 25 °C



12 Forward character. of reverse diode

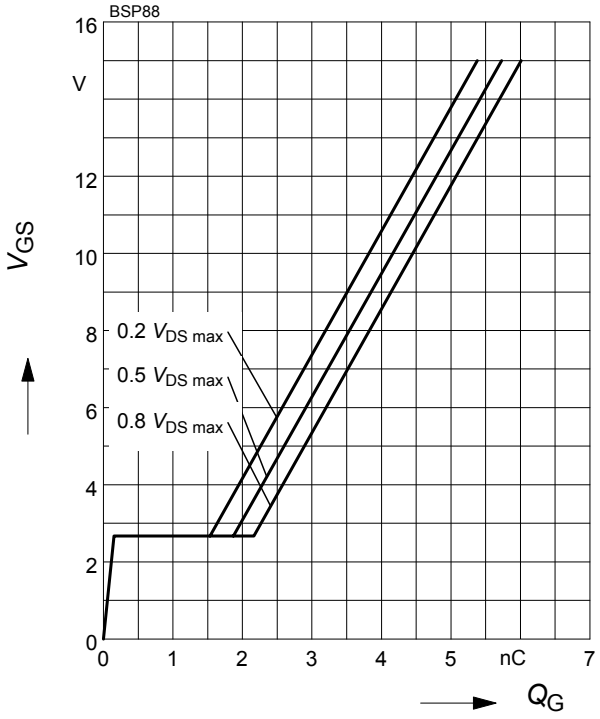
$I_F = f(V_{SD})$

parameter: T_j



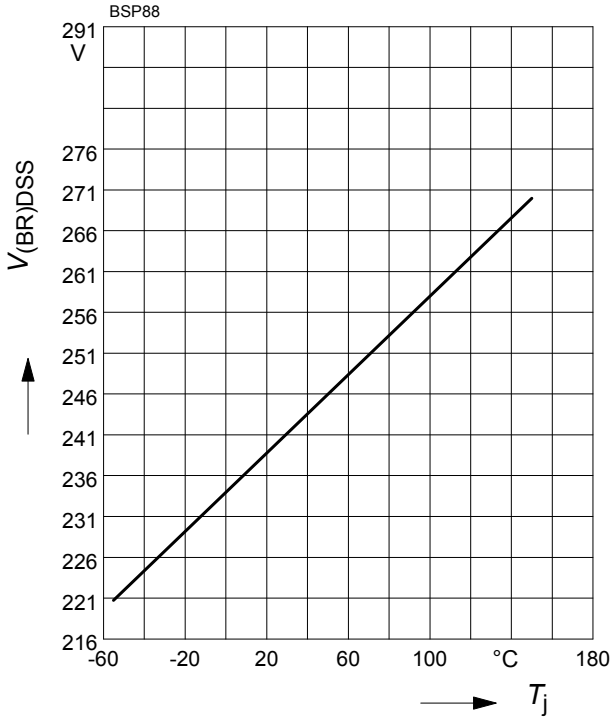
13 Typ. gate charge

$V_{GS} = f\ (Q_G)$; parameter: V_{DS} ,
$I_D = 0.35$ A pulsed, $T_j = 25$ °C



14 Drain-source breakdown voltage

$V_{(BR)DSS} = f\ (T_j)$



Published by
Infineon Technologies AG
81726 Munich, Germany
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